

Distributed by:



www.Jameco.com ♦ 1-800-831-4242

The content and copyrights of the attached
material are the property of its owner.

Jameco Part Number 835294

SN54HC112, SN74HC112 DUAL J-K NEGATIVE-EDGE-TRIGGERED FLIP-FLOPS WITH CLEAR AND PRESET

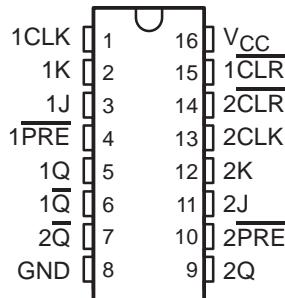
SCLS099F – DECEMBER 1982 – REVISED SEPTEMBER 2003

- Wide Operating Voltage Range of 2 V to 6 V
- Outputs Can Drive Up To 10 LSTTL Loads
- Low Power Consumption, 40- μ A Max I_{CC}
- Typical $t_{pd} = 13$ ns
- ± 4 -mA Output Drive at 5 V
- Low Input Current of 1 μ A Max

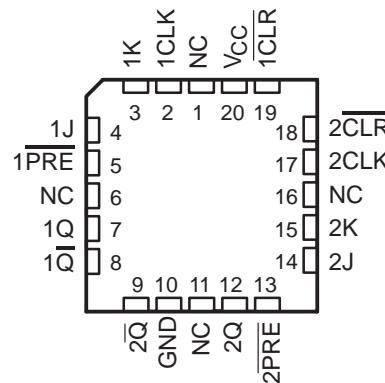
description/ordering information

The 'HC112 devices contain two independent J-K negative-edge-triggered flip-flops. A low level at the preset (\overline{PRE}) or clear (\overline{CLR}) inputs sets or resets the outputs, regardless of the levels of the other inputs. When \overline{PRE} and \overline{CLR} are inactive (high), data at the J and K inputs meeting the setup time requirements are transferred to the outputs on the negative-going edge of the clock (CLK) pulse. Clock triggering occurs at a voltage level and is not directly related to the fall time of the CLK pulse. Following the hold-time interval, data at the J and K inputs may be changed without affecting the levels at the outputs. These versatile flip-flops perform as toggle flip-flops by tying J and K high.

SN54HC112 . . . J OR W PACKAGE
SN74HC112 . . . D OR N PACKAGE
(TOP VIEW)



SN54HC112 . . . FK PACKAGE
(TOP VIEW)



NC – No internal connection

ORDERING INFORMATION

TA	PACKAGE†		ORDERABLE PART NUMBER	TOP-SIDE MARKING
-40°C to 85°C	PDIP – N	Tube of 25	SN74HC112N	SN74HC112N
	SOIC – D	Tube of 40	SN74HC112D	HC112
		Reel of 2500	SN74HC112DR	
		Reel of 250	SN74HC112DT	
-55°C to 125°C	CDIP – J	Tube of 25	SNJ54HC112J	SNJ54HC112J
	CFP – W	Tube of 150	SNJ54HC112W	SNJ54HC112W
	LCCC – FK	Tube of 55	SNJ54HC112FK	SNJ54HC112FK

† Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

PRODUCTION DATA information is current as of publication date. Products conform to specifications per the terms of Texas Instruments standard warranty. Production processing does not necessarily include testing of all parameters.



POST OFFICE BOX 655303 • DALLAS, TEXAS 75265

Copyright © 2003, Texas Instruments Incorporated
On products compliant to MIL-PRF-38535, all parameters are tested unless otherwise noted. On all other products, production processing does not necessarily include testing of all parameters.

SN54HC112, SN74HC112
DUAL J-K NEGATIVE-EDGE-TRIGGERED FLIP-FLOPS
WITH CLEAR AND PRESET

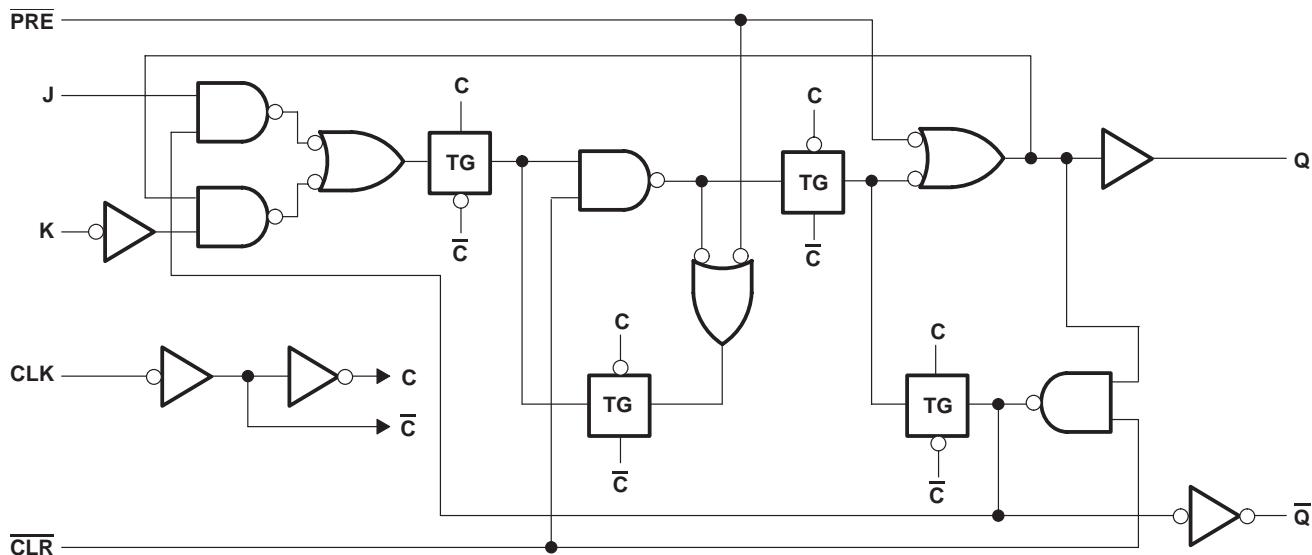
SCLS099F – DECEMBER 1982 – REVISED SEPTEMBER 2003

FUNCTION TABLE

INPUTS					OUTPUTS	
PRE	CLR	CLK	J	K	Q	\bar{Q}
L	H	X	X	X	H	L
H	L	X	X	X	L	H
L	L	X	X	X	H†	H†
H	H	↓	L	L	Q_0	\bar{Q}_0
H	H	↓	H	L	H	L
H	H	↓	L	H	L	H
H	H	↓	H	H	Toggle	
H	H	H	X	X	Q_0	\bar{Q}_0

† This configuration is nonstable; that is, it does not persist when either PRE or CLR returns to its inactive (high) level.

logic diagram, each flip-flop (positive logic)



absolute maximum ratings over operating free-air temperature range†

† Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output voltage ratings may be exceeded if the input and output current ratings are observed.
2. The package thermal impedance is calculated in accordance with JEDEC 51-7.

recommended operating conditions (see Note 3)

			SN54HC112			SN74HC112			UNIT
			MIN	NOM	MAX	MIN	NOM	MAX	
V _{CC}	Supply voltage		2	5	6	2	5	6	V
V _{IH}	High-level input voltage	V _{CC} = 2 V	1.5		1.5				V
		V _{CC} = 4.5 V	3.15		3.15				
		V _{CC} = 6 V	4.2		4.2				
V _{IL}	Low-level input voltage	V _{CC} = 2 V		0.5			0.5		V
		V _{CC} = 4.5 V		1.35			1.35		
		V _{CC} = 6 V		1.8			1.8		
V _I	Input voltage		0	V _{CC}	0	V _{CC}		V _{CC}	V
V _O	Output voltage		0	V _{CC}	0	V _{CC}		V _{CC}	V
t _{tr} [†]	Input transition (rise and fall) time	V _{CC} = 2 V		1000			1000		ns
		V _{CC} = 4.5 V		500			500		
		V _{CC} = 6 V		400			400		
T _A	Operating free-air temperature		-55	125	-40	85		°C	

‡ If this device is used in the threshold region (from $V_{IL\max} = 0.5\text{ V}$ to $V_{IH\min} = 1.5\text{ V}$), there is a potential to go into the wrong state from induced grounding, causing double clocking. Operating with the inputs at $t_t = 1000\text{ ns}$ and $V_{CC} = 2\text{ V}$ does not damage the device; however, functionally, the CLK inputs are not ensured while in the shift, count, or toggle operating modes.

NOTE 3: All unused inputs of the device must be held at VCC or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.

SN54HC112, SN74HC112
DUAL J-K NEGATIVE-EDGE-TRIGGERED FLIP-FLOPS
WITH CLEAR AND PRESET

SCLS099F – DECEMBER 1982 – REVISED SEPTEMBER 2003

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS	V _{CC}	T _A = 25°C			SN54HC112	SN74HC112	UNIT
			MIN	TYP	MAX	MIN	MAX	
V _{OH}	V _I = V _{IH} or V _{IL}	I _{OH} = -20 µA	2 V	1.9	1.998	1.9	1.9	V
			4.5 V	4.4	4.499	4.4	4.4	
			6 V	5.9	5.999	5.9	5.9	
		I _{OH} = -4 mA	4.5 V	3.98	4.3	3.7	3.84	
		I _{OH} = -5.2 mA	6 V	5.48	5.8	5.2	5.34	
V _{OL}	V _I = V _{IH} or V _{IL}	I _{OL} = 20 µA	2 V	0.002	0.1	0.1	0.1	V
			4.5 V	0.001	0.1	0.1	0.1	
			6 V	0.001	0.1	0.1	0.1	
		I _{OL} = 4 mA	4.5 V	0.17	0.26	0.4	0.33	
		I _{OL} = 5.2 mA	6 V	0.15	0.26	0.4	0.33	
I _I	V _I = V _{CC} or 0	6 V	±0.1	±100		±1000	±1000	nA
I _{CC}	V _I = V _{CC} or 0, I _O = 0	6 V			4	80	40	µA
C _i		2 V to 6 V		3	10	10	10	pF

timing requirements over recommended operating free-air temperature range (unless otherwise noted)

		V _{CC}	T _A = 25°C		SN54HC112	SN74HC112	UNIT
			MIN	MAX	MIN	MAX	
f _{clock}	Clock frequency	2 V		5	3.4	4	MHz
		4.5 V		25	17	20	
		6 V		29	20	24	
t _w	Pulse duration	PRE or CLR low	2 V	100	150	125	ns
			4.5 V	20	30	25	
			6 V	17	25	21	
		CLK high or low	2 V	100	150	125	
			4.5 V	20	30	25	
			6 V	17	25	21	
	Setup time before CLK↓	Data (J, K)	2 V	100	150	125	ns
			4.5 V	20	30	25	
			6 V	17	25	21	
		PRE or CLR inactive	2 V	100	150	125	
			4.5 V	20	30	25	
			6 V	17	25	21	
t _h	Hold time, data after CLK↓	2 V	0	0	0	0	ns
		4.5 V	0	0	0	0	
		6 V	0	0	0	0	

SN54HC112, SN74HC112
DUAL J-K NEGATIVE-EDGE-TRIGGERED FLIP-FLOPS
WITH CLEAR AND PRESET

SCLS099F – DECEMBER 1982 – REVISED SEPTEMBER 2003

switching characteristics over recommended operating free-air temperature range, $C_L = 50 \text{ pF}$ (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	V_{CC}	$T_A = 25^\circ\text{C}$			SN54HC112		SN74HC112		UNIT
				MIN	TYP	MAX	MIN	MAX	MIN	MAX	
f_{max}			2 V	5	10		3.4		4		MHz
			4.5 V	25	50		17		20		
			6 V	29	60		20		24		
t_{pd}	\overline{PRE} or \overline{CLR}	Q or \overline{Q}	2 V	54	165		245		205		ns
			4.5 V	16	33		49		41		
			6 V	13	28		42		35		
	CLK	Q or \overline{Q}	2 V	56	125		185		155		
			4.5 V	16	25		37		31		
			6 V	13	21		31		26		
t_t		Q or \overline{Q}	2 V	29	75		110		95		ns
			4.5 V	9	15		22		19		
			6 V	8	13		19		16		

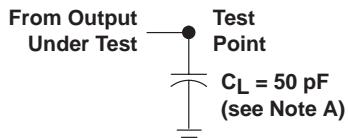
operating characteristics, $T_A = 25^\circ\text{C}$

PARAMETER	TEST CONDITIONS	TYP	UNIT
C_{pd} Power dissipation capacitance	No load	35	pF

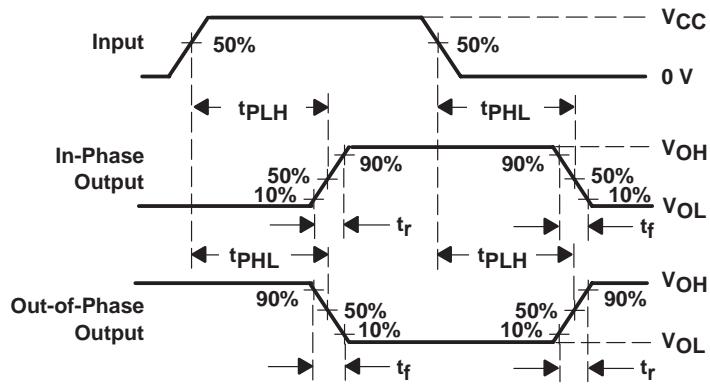
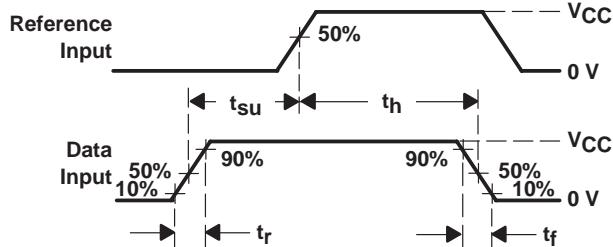
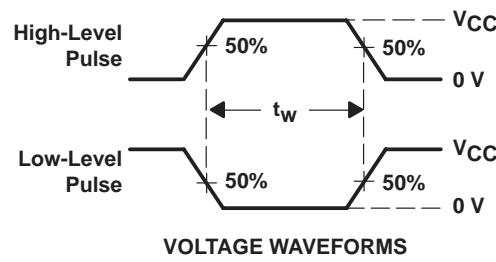
SN54HC112, SN74HC112
DUAL J-K NEGATIVE-EDGE-TRIGGERED FLIP-FLOPS
WITH CLEAR AND PRESET

SCLS099F – DECEMBER 1982 – REVISED SEPTEMBER 2003

PARAMETER MEASUREMENT INFORMATION



LOAD CIRCUIT



NOTES: A. C_L includes probe and test-fixture capacitance.
B. Phase relationships between waveforms were chosen arbitrarily. All input pulses are supplied by generators having the following characteristics: PRR ≤ 1 MHz, $Z_O = 50 \Omega$, $t_r = 6$ ns, $t_f = 6$ ns.
C. For clock inputs, f_{\max} is measured when the input duty cycle is 50%.
D. The outputs are measured one at a time with one input transition per measurement.
E. t_{PLH} and t_{PHL} are the same as t_{pd} .

Figure 1. Load Circuit and Voltage Waveforms

PACKAGING INFORMATION

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
84088012A	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type
8408801EA	ACTIVE	CDIP	J	16	1	TBD	A42 SNPB	N / A for Pkg Type
8408801FA	ACTIVE	CFP	W	16	1	TBD	A42	N / A for Pkg Type
JM38510/65305BEA	ACTIVE	CDIP	J	16	1	TBD	A42 SNPB	N / A for Pkg Type
SN54HC112J	ACTIVE	CDIP	J	16	1	TBD	A42 SNPB	N / A for Pkg Type
SN74HC112D	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74HC112DE4	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74HC112DR	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74HC112DRE4	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74HC112DT	ACTIVE	SOIC	D	16	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74HC112DTE4	ACTIVE	SOIC	D	16	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74HC112N	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN74HC112N3	OBsolete	PDIP	N	16		TBD	Call TI	Call TI
SN74HC112NE4	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SNJ54HC112FK	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type
SNJ54HC112J	ACTIVE	CDIP	J	16	1	TBD	A42 SNPB	N / A for Pkg Type
SNJ54HC112W	ACTIVE	CFP	W	16	1	TBD	A42	N / A for Pkg Type

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBsolete: TI has discontinued the production of the device.

⁽²⁾ Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

⁽³⁾ MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

Important Information and Disclaimer: The information provided on this page represents TI's knowledge and belief as of the date that it is provided. TI bases its knowledge and belief on information provided by third parties, and makes no representation or warranty as to the accuracy of such information. Efforts are underway to better integrate information from third parties. TI has taken and continues to take

reasonable steps to provide representative and accurate information but may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.

In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

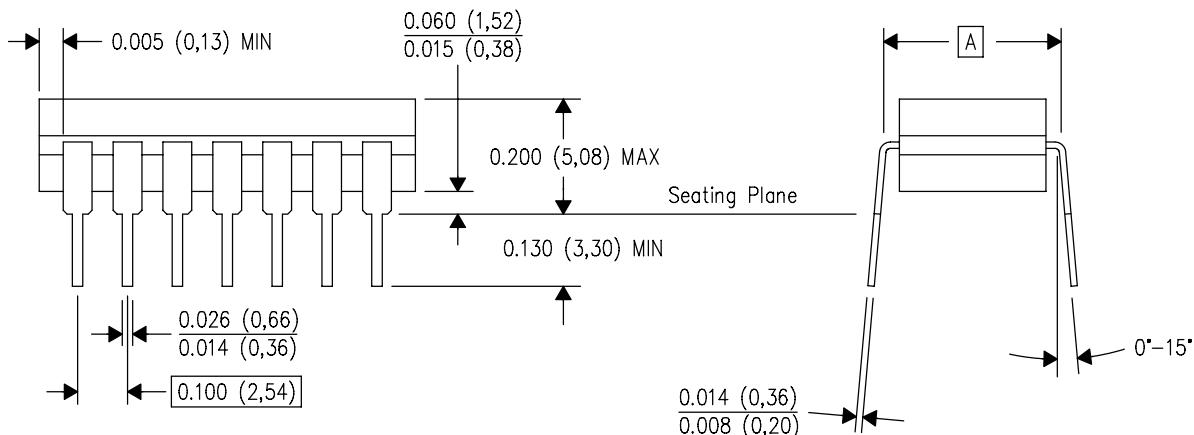
J (R-GDIP-T**)

14 LEADS SHOWN

CERAMIC DUAL IN-LINE PACKAGE



PINS ** DIM	14	16	18	20
A	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC
B MAX	0.785 (19,94)	.840 (21,34)	0.960 (24,38)	1.060 (26,92)
B MIN	—	—	—	—
C MAX	0.300 (7,62)	0.300 (7,62)	0.310 (7,87)	0.300 (7,62)
C MIN	0.245 (6,22)	0.245 (6,22)	0.220 (5,59)	0.245 (6,22)

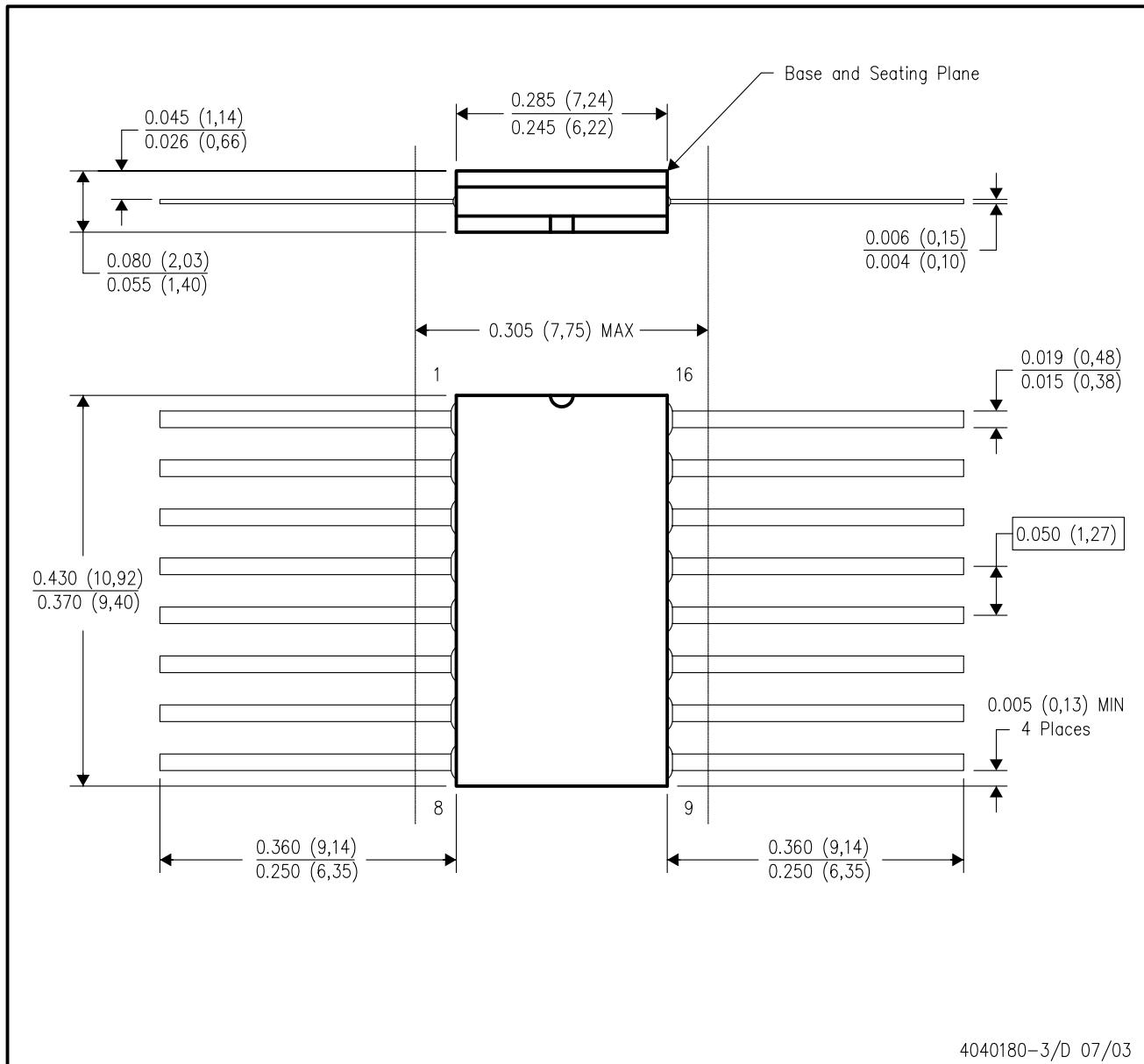


4040083/F 03/03

NOTES: A. All linear dimensions are in inches (millimeters).
B. This drawing is subject to change without notice.
C. This package is hermetically sealed with a ceramic lid using glass frit.
D. Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
E. Falls within MIL STD 1835 GDIP1-T14, GDIP1-T16, GDIP1-T18 and GDIP1-T20.

W (R-GDFP-F16)

CERAMIC DUAL FLATPACK



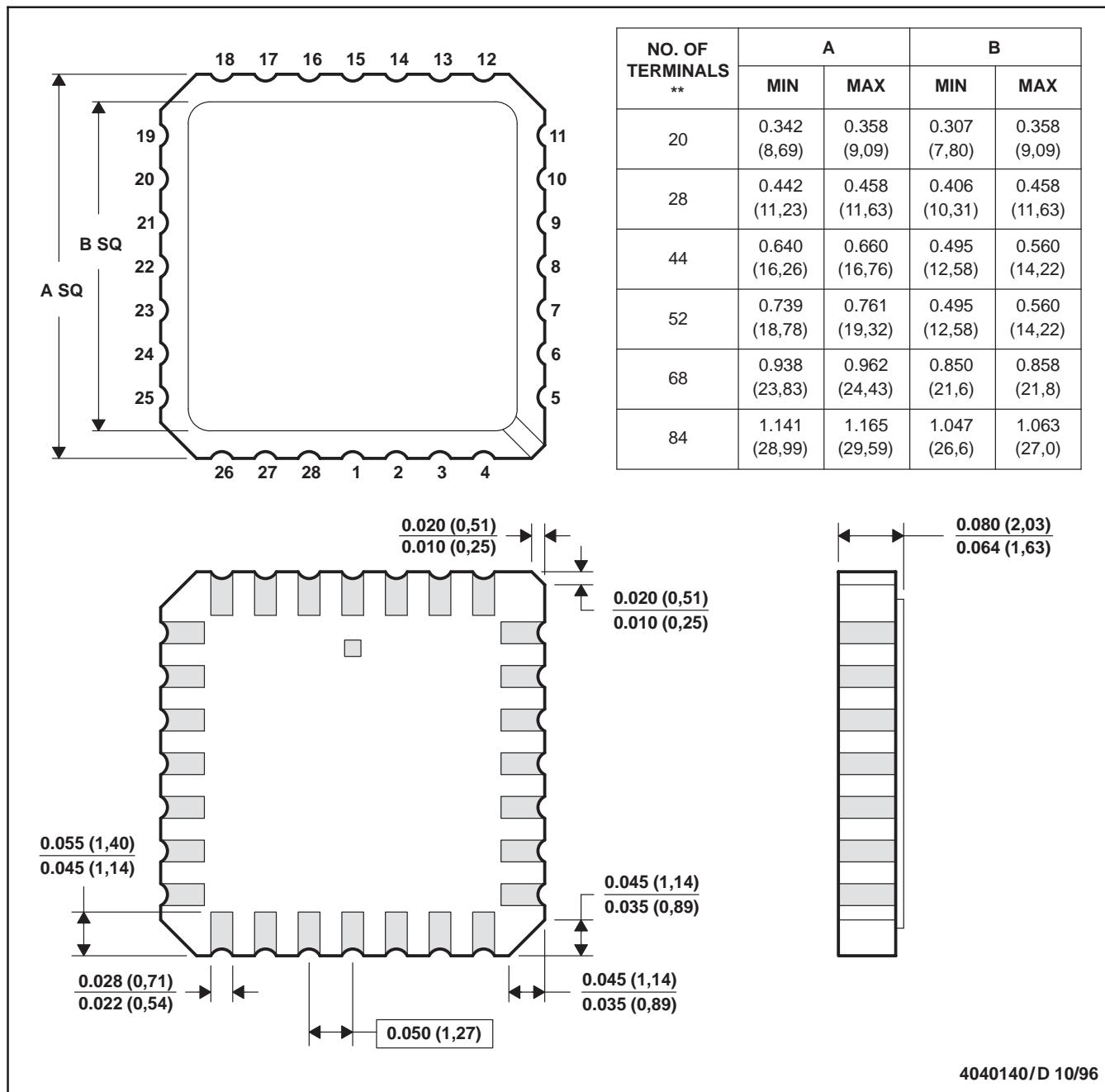
NOTES:

- All linear dimensions are in inches (millimeters).
- This drawing is subject to change without notice.
- This package can be hermetically sealed with a ceramic lid using glass frit.
- Index point is provided on cap for terminal identification only.
- Falls within MIL-STD 1835 GDFP1-F16 and JEDEC MO-092AC

FK (S-CQCC-N**)

LEADLESS CERAMIC CHIP CARRIER

28 TERMINAL SHOWN



NOTES:

- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. This package can be hermetically sealed with a metal lid.
- D. The terminals are gold plated.
- E. Falls within JEDEC MS-004

N (R-PDIP-T**)

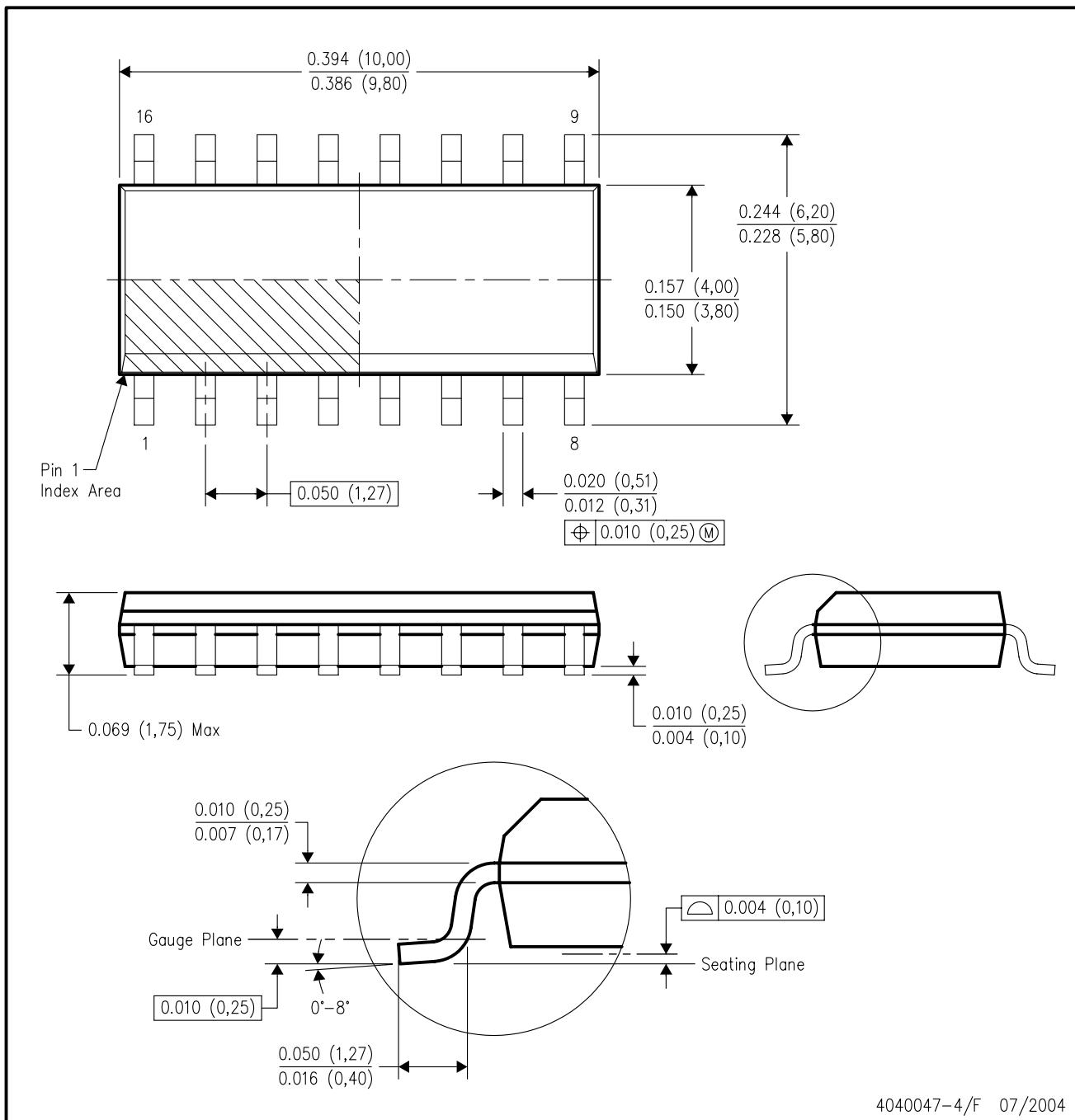
16 PINS SHOWN

PLASTIC DUAL-IN-LINE PACKAGE



D (R-PDSO-G16)

PLASTIC SMALL-OUTLINE PACKAGE



4040047-4/F 07/2004

NOTES:

- All linear dimensions are in inches (millimeters).
- This drawing is subject to change without notice.
- Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).
- Falls within JEDEC MS-012 variation AC.

IMPORTANT NOTICE

Texas Instruments Incorporated and its subsidiaries (TI) reserve the right to make corrections, modifications, enhancements, improvements, and other changes to its products and services at any time and to discontinue any product or service without notice. Customers should obtain the latest relevant information before placing orders and should verify that such information is current and complete. All products are sold subject to TI's terms and conditions of sale supplied at the time of order acknowledgment.

TI warrants performance of its hardware products to the specifications applicable at the time of sale in accordance with TI's standard warranty. Testing and other quality control techniques are used to the extent TI deems necessary to support this warranty. Except where mandated by government requirements, testing of all parameters of each product is not necessarily performed.

TI assumes no liability for applications assistance or customer product design. Customers are responsible for their products and applications using TI components. To minimize the risks associated with customer products and applications, customers should provide adequate design and operating safeguards.

TI does not warrant or represent that any license, either express or implied, is granted under any TI patent right, copyright, mask work right, or other TI intellectual property right relating to any combination, machine, or process in which TI products or services are used. Information published by TI regarding third-party products or services does not constitute a license from TI to use such products or services or a warranty or endorsement thereof. Use of such information may require a license from a third party under the patents or other intellectual property of the third party, or a license from TI under the patents or other intellectual property of TI.

Reproduction of information in TI data books or data sheets is permissible only if reproduction is without alteration and is accompanied by all associated warranties, conditions, limitations, and notices. Reproduction of this information with alteration is an unfair and deceptive business practice. TI is not responsible or liable for such altered documentation.

Resale of TI products or services with statements different from or beyond the parameters stated by TI for that product or service voids all express and any implied warranties for the associated TI product or service and is an unfair and deceptive business practice. TI is not responsible or liable for any such statements.

Following are URLs where you can obtain information on other Texas Instruments products and application solutions:

Products		Applications	
Amplifiers	amplifier.ti.com	Audio	www.ti.com/audio
Data Converters	dataconverter.ti.com	Automotive	www.ti.com/automotive
DSP	dsp.ti.com	Broadband	www.ti.com/broadband
Interface	interface.ti.com	Digital Control	www.ti.com/digitalcontrol
Logic	logic.ti.com	Military	www.ti.com/military
Power Mgmt	power.ti.com	Optical Networking	www.ti.com/opticalnetwork
Microcontrollers	microcontroller.ti.com	Security	www.ti.com/security
Low Power Wireless	www.ti.com/lpw	Telephony	www.ti.com/telephony
		Video & Imaging	www.ti.com/video
		Wireless	www.ti.com/wireless

Mailing Address: Texas Instruments
Post Office Box 655303 Dallas, Texas 75265

Copyright © 2006, Texas Instruments Incorporated